SiFOC
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企业宣传册
BUSINESS BROCHURE

思孚科新材料（深圳）有限公司
SiFOC New Material (Shenzhen) Co., Ltd.

SiFOC New Material (Shenzhen) Co., Ltd.

Company Profile

SiFOC New Material (Shenzhen) Co., Ltd.

Website:http://www.sifoc-materials.com

SiFOC New Material is committed to providing creative and technologically advanced **TIM** for end - customers. At the same time, it continues to conduct technical research, build a domestic independent material brand, accelerate the development of world - class electronic packaging materials, and enable **heat - dissipating materials** to serve the world!

The company focus on providing high - quality **thermal conductive and heat - dissipating packaging materials** and other products. These products are mainly applied in industries such as new energy vehicles, industrial 5G communication, aviation, electronics, and electrical appliances. The products are mainly divided into several major categories, including thermal conductive silicone pads, non - silicone thermal conductive pads, thermal conductive greases, thermal conductive potting adhesives, thermal conductive clay, thermal conductive gels, thermal conductive phase - change materials, thermal conductive insulating sheets, and thermal conductive graphite sheets.With advanced technology and high - quality services, the company occupies an important position in the market and has broad development prospects.

SiFOC New Material (Shenzhen) Co., Ltd.
Office Environment

SiFOC 思孚科

SiFOC New Material (Shenzhen) Co., Ltd.

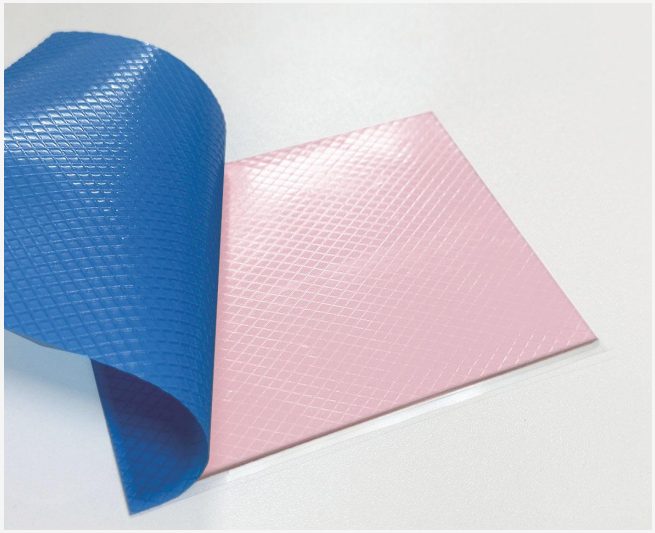
Experimental Testing Equipment

SiFOC New Material (Shenzhen) Co., Ltd.

Product Catalog

SiFOC New Material (Shenzhen) Co., Ltd.

Thermal Conductive Silicone Pad-SFP series



Product Features

- Good surface wettability can fully reduce the contact thermal resistance.
- Soft and highly compressible.
- Low oil seepage.
- Low volatility.

Typical Applications

- 5G communication base stations, wireless infrastructure, optical modules.
- LCD, PDP, and laser TV displays.
- Industrial, LED lighting, and power modules.
- Automotive electronics and power batteries.

Storage and Shelf Life

- Temperature:25±5℃; Humidity ≤ 65%.
- ≤ 12months

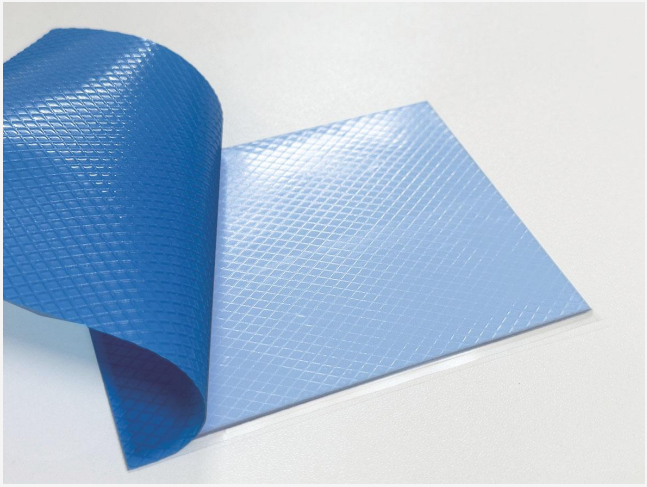
Ordering Information

- Sheet packaging.
- Customized thickness

Item	Unit	SFP200	SFP400	SFP600
Color	--	Green	Fuchsia	Grey
Thickness	mm	0.5-10	0.5-10	0.5-10
Hardness	Shore00	50-90	50-90	50-90
Density	g/cm³	2.8±0.1	3.1±0.1	3.4±0.1
Heat conductivity coefficient	W/m*k	2.0±0.2	4.0±0.2	6.0±0.2
Thermal resistance @20psi、1mm	℃*cm²/W	3.68	2.15	1.81
Compressibility@20psi	%	35	30	20
Volume resistivity	Ω*cm	≥10^{13}	≥10^{13}	≥10^{10}
Dielectric breakdown voltage @1mm	KV	≥10	≥10	≥10
Flame retardant rating	--	V-0	V-0	V-0
Operation Temp.	℃	-40-200	-40-150	-40-150

SiFOC New Material (Shenzhen) Co., Ltd.

High - Thermal - Conductivity Silicone Pad -SFP series



Storage and shelft life

- Temperature 25±5℃， Humidity≤65%
- ≤12个months

Product Features

- Good surface wettability can fully reduce the contact thermal resistance.
- Soft and highly compressible.
- Low oil seepage.
- Low volatility.
- High thermal conductivity.

Typical Applications

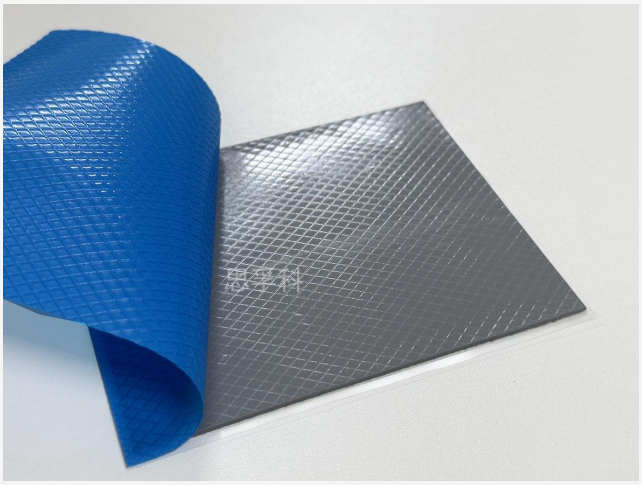
- 5G communication base stations, wireless infrastructure, optical modules
- LCD, PDP and laser TV displays
- Industrial applications, LED lighting and power modules
- Automotive electronics and power batteries
- Hard disk drives and solid - state drive storage devices

Ordering Information

- Sheet packaging.
- Customized thickness

Item	Unit	SFP800	SFP1000	SFP1500
Color	--	Blue	Grey	Grey
Thickness	mm	0.5-10	0.8-10	1-10
Hardness	Shore00	50-90	60-90	60-90
Density	g/cm³	3.5±0.1	3.3±0.1	3.5±0.1
Heat conductivity coefficient	W/m*k	8.0±0.2	10.0±0.2	15.0±0.2
Thermal resistance @20psi、1mm	℃*cm²/W	1.65	1.25	1.02
Compressibility@20psi	%	30	20	10
Volume resistivity	Ω*cm	≥10^{10}	≥10^{10}	≥10^{8}
Dielectric breakdown voltage @1mm	KV	≥10	≥10	≥10
Flame retardant rating	--	V-0	V-0	V-0
Operation Temp.	℃	-40-150	-40-150	-40-150

Low - Density Thermal Conductive Silicone Pad -SFPY series



Storage and shelft life

- Temperature 25±5℃， Humidity≤65%
- ≤12个months

Product Features

- Good surface wettability effectively reduces contact thermal resistance.
- Soft and highly compressible.
- Low oil seepage.
- Low volatility.
- Low density.

Typical Applications

- 5G communication base stations, wireless infrastructure, optical modules
- LCD, PDP and laser TV displays
- Industrial applications, LED lighting and power modules
- Automotive electronics and power batteries
- Hard disk drives and solid-state drive storage devices

Ordering Information

- Sheet packaging.
- Customized thickness

Item	单位	SFP100Y	SFP200Y	SFP300Y
Color	--	Yellow	Green	Pink
Thickness	mm	0.5-10	0.5-10	0.5-10
Hardness	Shore00	50-90	50-90	50-90
Density	g/cm³	1.7±0.1	2.3±0.1	2.0±0.1
Heat conductivity coefficient	W/m*k	1.0±0.2	2.0±0.2	3.0±0.2
Thermal resistance @20psi、1mm	℃*cm²/W	9.89	5.76	3.96
Compressibility@20psi	%	35	30	20
Volume resistivity	Ω*cm	≥10^{13}	≥10^{13}	≥10^{13}
Dielectric breakdown voltage @1mm	KV	≥10	≥10	≥10
Flame retardant rating	--	V-0	V-0	V-0
Operation Temp.	℃	-40-200	-40-200	-40-200

Thermal Conductive Grease-SFG Series

Product Features

• Excellent thermal conductivity and high reliability.
• The surface is wettable, effectively reducing the interfacial thermal resistance.
• Low volatility, maintaining the paste state for a long time.
• Precise viscosity, facilitating scraping and easy to operate.
• Made of environmentally friendly raw materials, with no release of harmful gases.

Typical Applications

• Thermal conduction between microchips such as CPU/GPU graphics processing units and heat dissipation devices.
• Between power resistors and their bases.
• In thermoelectric cooling devices.
• Between temperature regulators and assembly surfaces.
• In industries such as LED lighting.

Storage and shelft life

• Temperature 25±5℃，Humidity≤65%
• ≤12个months

Ordering Information

Regular packaging: 300ml per tube, 1KG per can, 5KG per can, 10KG per barrel, 20KG per barrel.

Item	Unit	SFG100	SFG200	SFG300
Color	--	White	Grey	Grey
Density	g/cm³	2.5±0.1	2.6±0.1	2.7±0.1
Heat conductivity coefficient	W/m*k	1.0±0.2	2.0±0.2	3.0±0.2
Thermal resistance @60psi	℃*in²/W	0.02	0.015	0.012
Cone penetration	1/10	300	300	280
Oil bleeding rate	%	≤1	≤1	≤1
Volatile	%	≤1	≤1	≤1
Operation Temp.	℃	-40-150	-40-150	-40-150

SiFOC New Material (Shenzhen) Co., Ltd.

Thermal Conductive Silicone Grease with Low Thermal Resistance-SFG series

Product Features

- Excellent thermal conductivity, high reliability and extremely low thermal resistance.
- The surface has wettability, effectively reducing the interfacial thermal resistance.
- Low volatility, maintaining the paste state for a long time.
- Precise viscosity, making it convenient for scraping and easy to operate.
- Made of environmentally friendly raw materials, with no release of harmful gases.

Typical Applications

- Thermal conduction between microchips such as CPU and GPU graphics processors and heat dissipation devices.
- Between power resistors and their bases.
- In thermoelectric cooling devices.
- Between temperature regulators and assembly surfaces.
- In industries like LED lighting.

Storage and shelft life

- Temperature 25±5℃，Humidity≤65%
- ≤12个months

Ordering Information

Conventional packaging: 300ml per tube, 1KG per can, 5KG per can, 10KG per barrel, 20KG per barrel.

Item	Unit	SFG200S	SFG400S	SFG600S
Color	--	Grey	Grey	Grey
Density	g/cm³	2.5±0.1	2.6±0.1	2.7±0.1
Heat conductivity coefficient	W/m*k	2.0±0.2	4.0±0.2	6.0±0.2
Thermal resistance @60psi	℃*in²/W	0.012	0.01	0.009
Cone penetration	1/10	300	280	260
Oil bleeding rate	%	≤1	≤1	≤1
Volatile	%	≤1	≤1	≤1
Operation Temp.	℃	-40-150	-40-150	-40-150

Thermal Conductive Clay-SFC series

Product Features

- High thermal conductivity and low thermal resistance, with good wettability.
- No sedimentation, no flowing. It can fill any uneven gaps.
- It is soft, stress-free and can be compressed to a thickness of 0.1mm.

Typical Applications:

- Wireless communication electronic hardware devices such as set-top boxes, network terminals, and 5G mobile phones.
- Network devices in mainframes or small offices, chassis, or related heat dissipation modules.
- Automotive electronic application devices.
- Electronic medical and power supply equipment.
- Microprocessors, memory chips, and graphics processing units.

Storage and shelft life

- Temperature 25±5℃，Humidity≤65%
- ≤12个months

Ordering Information

Barrel packaging: 1 kg/barrel, 5 kg/barrel, 10 kg/barrel, 20 kg/barrel.
Tube packaging: 300 ML, 2600 ML.

Item	Unit	SFC100	SFC300	SFC600
Color	--	White	Pink	Blue
Density	g/cm³	2.2±0.1	3.0±0.1	3.4±0.1
Heat conductivity coefficient	W/m*k	1.0	3.0	6.0
Thermal resistance @60psi	℃*in²/W	0.089	0.048	0.045
Cone penetration	g	0-5	0-5	0-5
Oil bleeding rate	Ω*cm	≥10^{13}	≥10^{13}	≥10^{13}
Volatile matte	KV	≥10	≥10	≥10
Flame retardant rating	--	V-0	V-0	V-0
Operation Temp.	℃	-40-150	-40-150	-40-150

One Component thermal Conductive Gel--SFSG series

Product Features

- Single-component , won't solidify, with high reliability.
- Excellent application effect for irregular structural gaps.
- Good electrical insulation performance, meeting the requirements of electronic devices.
- Good mechanical properties and weather resistance.

Typical Applications:

- Wireless communication electronic hardware devices such as set-top boxes, network terminals, 5G mobile phones, etc.
- Network devices in mainframes or small offices, chassis or related heat dissipation modules.
- Automotive electronic application devices, electronic medical devices, power supply devices.
- Microprocessors, memory chips and graphics processing units.

Storage and shelft life

- Temperature 25±5℃，Humidity≤65%
- ≤12个months

Ordering Information

- Packaging in syringes (or cans).
- Single-component volume: 30cc / 300cc.

Item	Unit	SFSG300	SFSG600	SFSG1000
Color	--	Pink	Blue	Grey
Density	g/cm³	3.0±0.1	3.4±0.1	3.4±0.1
Heat conductivity coefficient	W/m*k	3.0	6.0	10.0
Thermal resistance @60psi	℃*in²/W	0.048	0.045	0.035
Cone penetration	g	30-40	30-40	20-30
Oil bleeding rate	Ω*cm	≥10^{13}	≥10^{10}	≥10^{8}
Volatile matte	KV	≥10	≥10	≥8
Flame retardant rating	--	V-0	V-0	V-0
Operation Temp.	℃	-40-150	-40-150	-40-150

SiFOC New Material (Shenzhen) Co., Ltd.

Two Component thermal Conductive Gel-SFTF series

Product Features

- Used in a 1:1 ratio and can be 100% cured.
- Can be cured at room temperature or by heating.
- Excellent fluidity and electrical insulation performance.
- Excellent mechanical properties and weather resistance.

Typical Applications:

- 5G communication base stations, wireless infrastructure, optical modules
- LCD, PDP and laser TV displays
- Industrial applications, LED lighting and power modules
- Automotive electronics and power batteries
- Hard disk drives and solid-state drive storage devices

Storage and shelft life

- Temperature 25±5℃，Humidity≤65%
- ≤12个months

Ordering Information

- Packaging in syringes (or cans).
- Two-component: 1:1 mixture. Syringe volume: 50cc / 400cc.

Item	Unit	SFTF200	SFTF400	SFTF600
Color before mixing	--	A green、B white	A pink、B white	A blue、B white
Color after mixing	--	green	pink	blue
Density	g/cm³	2.3±0.1	3.2±0.1	3.4±0.1
Ratio	g	1： 1		
Extrusion Rate @90psi、50ml	g	30±10	30±10	30±10
Hardness	Shore00	50-90	50-90	50-90
Heat conduction coefficient	W/m*k	2.0	4.0	6.0
Tack-free time@25℃	min	60-90	60-90	60-90
Curing time @25℃	h	3-5	3-5	3-5
Curing time @100℃	min	30	30	30
Volume resistivity	Ω*cm	≥10^{13}	≥10^{13}	≥10^{13}
Dielectric breakdown voltage@1mm	KV	≥10	≥10	≥10
Flame retardant rating	--	V-0	V-0	V-0
Operation Temp.	℃	-40-150	-40-150	-40-150

Thermal Conductive Potting Adhesive-SF series

Product Features

- Excellent thermal conductivity and low viscosity.
- Good fluidity and rapid bubble removal.
- Cures at room temperature, and heating can accelerate the curing speed.
- Moisture-proof and shock-resistant, with no corrosion to the base material.

Typical Applications:

- High-frequency electronic components such as power modules, inverters, and ballasts.
- Electronic control units and sensors.
- LED lighting components, as well as other suitable encapsulation applications in the industrial field.

Storage and shelft life

- Temperature 25±5℃，Humidity≤65%
- ≤12个months

Ordering Information

- Packaging in cans.
- Weight: Packaged in 400cc tubes, 12.5kg barrels, 25kg barrels.

Item	Unit	SF100	SF200	SF400
Color before mixing	--	A grey、B white	A grey、B white	A grey、B white
Viscosity before mixing@25℃	mpa*s	2500-3500	7000-9000	10000-15000
Viscosity after mixing @25℃	mpa*s	2500-3500	7000-9000	10000-15000
Density after mixing	g/cm³	2.0±0.1	2.8±0.1	3.0±0.1
Mixing ratio	g	1：1		
Hardness	Shore A	40-50	30-40	30-40
Heat conduction coefficient	W/m*k	1.0	2.0	4.0
Tack free time@25℃	min	60-90	60-90	60-90
Curing time @25℃	h	3-5	3-5	3-5
Curing time @100℃	min	30	30	30
Volume resistivity	Ω*cm	≥10^{13}	≥10^{13}	≥10^{12}
Dielectric breakdown voltage@1mm	KV	≥10	≥10	≥10
Flame retardant rating	--	V-0	V-0	V-0
Operation temp.	℃	-40-150	-40-150	-40-150

SiFOC New Material (Shenzhen) Co., Ltd.

Thermal Conductive Insulating Sheet-SFTM Series

Product Features

- Excellent insulating material.
- Smooth surface.
- Low installation pressure.
- UL94-V0 flame-retardant grade.
- Meeting RoHS standards and halogen-free requirements.
- Single-sided adhesive available. A1 (Total thickness after applying adhesive: 0.18mm).

Typical Applications

- Power equipment, automotive electronics, communication equipment, LED lighting network terminals.
- Storage devices, consumer electronics, security equipment.

Storage and shelft life

- Temperature 25±5℃，Humidity≤65%
- ≤12个months

Ordering Information

- Standard roll packaging.
- Product packaging specifications: (Width * Thickness) * Length: (505mm * 0.15mm) * 60m

Item	Unit	SFTM100	SFTM200	SFTM350
Color	--	Pink	Green	White
Thickness	mm	0.15	0.2	0.25
Hardness	ShoreA	85-95	85-95	85-95
Heat conduction coefficient	W/m*k	1.0	2.0	3.5
Thermal resistivity @20psi、0.15mm	℃*in²/W	0.76	0.65	0.5
Tensile strength	MPa	30	30	6
Elongation	%	5	3	1
Volume resistivity	Ω*cm	≥10^{13}	≥10^{13}	≥10^{13}
Dielectric breakdown voltage @1mm	KV	≥6	≥6	≥6
Flame retardant rating	--	V-0	V-0	V-0
Operation Temp.	℃	-40-200	-40-200	-40-200

SiFOC New Material (Shenzhen) Co., Ltd.

Thermal Conductive Phase Change Material -SFPC series

Product Features

- Extremely reliable stability with no silicone oil pump - out problem.
- Optimal surface wettability.
- Low contact thermal resistance under low pressure.
- Low application thickness and low thermal impedance.

Typical Applications

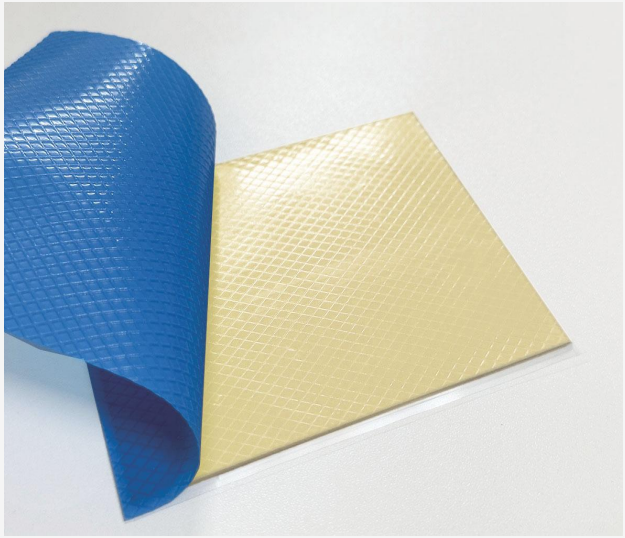
- Aerospace technology applications.
- Household appliances such as air conditioners, refrigerators, washing machines, and televisions.
- Display devices such as liquid crystal electronic screens of electrical equipment.
- Mobile communication devices.
- Power equipment.

Storage and shelft life

- Temperature:0±15℃，humidity≤65%
- ≤12个months

Item	Unit	SFPC200	SFPC500	SFPC850
Color	--	grey	grey	grey
Hardness	mm	0.15	0.20	0.25
Phase change Temp.	℃	45	48	48
Density	g/cm³	2.2±0.1	2.6±0.1	2.8±0.1
Heat conduction coefficient	W/m*k	2.0	5.0	8.5
Thermal resistivity @60psi、0.25mm	℃*in²/W	0.03	0.02	0.01
Volume resistivity	Ω*cm	≥10^{13}	≥10^{10}	≥10^{8}
Flame retardant rating	--	V-0	V-0	V-0
Operation temp.	℃	-40-200	-40-200	-40-200

Non - Silicone Thermal Conductive Pad-SFTP series



Typical Applications

- 5G communication base stations, wireless infrastructure, optical modules.
- LCD, PDP, and laser TV displays.
- Industrial, LED lighting, and power supply modules.
- Automotive electronics and power batteries.
- Hard disk drives and solid - state drive storage devices.

Product Features

- Good surface wettability can significantly reduce contact thermal resistance.
- Soft and with good compressibility.
- Low oil seepage.
- Low volatility.

Storage and shelft life

- Temperature 25±5℃，Humidity≤65%
- ≤12个months

Ordering Information

- Sheet packaging.
- Customized thickness

Item	Unit	SFTP200	SFTP400	SFTP600
Color	--	Blue	Fuchsia	Grey
Thickness	mm	0.5-10	0.5-10	0.5-10
Hardness	Shore00	50-90	50-90	50-90
Density	g/cm³	3.0±0.1	3.3±0.1	3.5±0.1
Heat conduction coeffient	W/m*k	2.0±0.2	4.0±0.2	6.0±0.2
Thermal resistivity @20psi、1mm	℃*cm²/W	2.56	1.85	1.62
Compression Ratio @20psi	%	35	30	20
Volume resistivity	Ω*cm	≥10^{13}	≥10^{13}	≥10^{13}
Dielectric breakdown voltage @1mm	KV	≥10	≥10	≥10
Flame retardant rating	--	V-0	V-0	V-0
Operation temp.	℃	-40-150	-40-150	-40-150

Epoxy Potting Adhesive-SFEP series

Product Features

• Moderate viscosity after mixing the two components, good leveling property, and easy to eliminate bubbles.
• Cured by heating, generates little heat during the curing process, and has an extremely low shrinkage rate.
• After curing, it has excellent flame retardancy and good performance in high and low temperature cycle resistance.
• Excellent water resistance, moisture resistance, oil resistance, corrosion resistance, and resistance to damp heat aging.

Typical Applications

• High-frequency electronic components such as power modules, inverters and ballasts.
• Electronic control units and sensors.
• LED lighting components, as well as potting applications for other suitable products in the industrial field.

Storage and Shelft life

• Temperature 25±5℃，Humidity≤65%
• ≤12个months

Ordering Information

• Canned packaging
• Product packaging specifications: Weight: 400cc per tube, 12.5kg per barrel, 25kg per barrel.

Item	Unit	SFEP070	SFEP120	SFEP200
Color before mixing	--	A black、B yellow	A black、B yellow	A black、B yellow
Viscosity A @40℃	mpa*s	30000-40000	35000-45000	40000-60000
Viscosity B @40℃	mpa*s	100-300	80-200	50-150
Viscosity after mixing @40℃	mpa*s	2500-3500	4000-6000	8000-12000
Mixing ratio	g	5：1		
Hardness	Shore D	80-90	80-90	80-90
Heat conduction coefficient	W/m*k	0.7	1.2	2.0
Curing time @85℃	h	2-3	2-3	2-3
Curing time @100℃	min	30-60	30-60	30-60
Volume resistivity	Ω*cm	≥10^{13}	≥10^{13}	≥10^{13}
Dielectric breakdown voltage @1mm	KV	≥10	≥10	≥10
Tensile strength	MPa	30-40	20-30	10-20
coefficient of linear expansion	ppm/k	30-40	15-25	10-20
Flame retardant rating	--	V-0	V-0	V-0
Operation temp.	℃	-40-200	-40-200	-40-200

PU Potting Adhesive-SFPU series

Product Features

- Moderate viscosity after the two components are mixed, with good leveling property and easy bubble bursting.
- Cured by heating, with little heat release during the curing process and an extremely low shrinkage rate.
- After curing, it has excellent flame retardancy and the performance of withstanding high and low temperature cycles.
- Excellent water resistance, moisture resistance, oil resistance, corrosion resistance and resistance to damp heat aging.

Typical Applications

• On-board chargers, battery assembly, power electronics, charging handles

Storage and Shelft life

• Temperature 25±5℃，Humidity≤65%

• ≤12个months

Ordering Information

- Canned packaging
- Product packaging specifications: Weight: 400cc per tube, 12.5kg per barrel, 25kg per barrel.

Item	Unit	SFPU070	SFPU120	SFPU200
Color before mixing	--	A black、B brown	A black、B brown	A black、B brown
A Viscosity@40℃	mpa*s	10000-14000	15000-20000	25000-35000
B Viscosity@40℃	mpa*s	100-300	80-200	50-150
Viscosity after mixing @40℃	mpa*s	6000-8000	8000-10000	12000-14000
Mixing ratio	g	5：1		
Hardness	Shore A	80-90	80-90	80-90
Heat conduction coefficient	W/m*k	0.7	1.2	2.0
Tack free time @25℃	min	60-90	60-90	60-90
Curing time @80℃	min	20-30	20-30	20-30
Volume Resistivity	Ω*cm	≥10^{13}	≥10^{13}	≥10^{13}
Dielectric breakdown voltage @1mm	KV	≥10	≥10	≥10
Tensile strength	MPa	30-40	20-30	10-20
Coefficient of linear expansion	ppm/k	30-40	15-25	10-20
Flame retardant rating	--	V-0	V-0	V-0
Operation temp.	℃	-40-150	-40-150	-40-150

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